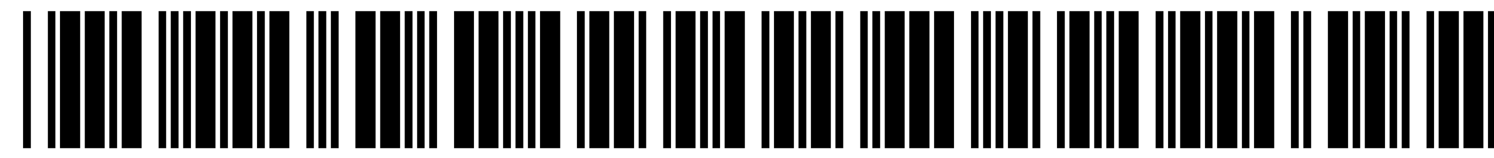

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(12) **United States Design Patent** (10) **Patent No.: US D891,382 S**
Koppa et al. (45) **Date of Patent: ** Jul. 28, 2020**

(54) **PROCESS SHIELD FOR A SUBSTRATE PROCESSING CHAMBER**

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(73) Assignee: **APPLIED MATERIALS, INC.**, Santa Clara, CA (US)

(**) Term: **15 Years**

(21) Appl. No.: **29/679,738**

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(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182, 184, 162, 199, 118, 122, 133; D24/232; 118/724, 725, 728, 729, 730, 118/733; 156/345.51, 345.52, 345.53
CPC C23C 16/455; C23C 16/45502; C23C 16/45517; C23C 16/4582; C23C 16/4583; C23C 16/4584; C23C 16/4585; C23C 16/4401; C23C 16/4402; C23C 16/4409; C23C 16/00; H01L 21/50; H01L 21/4817; H01L 21/4871; H01L 21/563; H01L 21/683; H01L 23/02; H01L 23/04; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/06; H01L 23/10; H01L 23/42; H05K 3/30; H01R 13/20; H01R 13/56; H01R 35/00
See application file for complete search history.

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(Continued)

Primary Examiner — Elizabeth J Oswecki
(74) *Attorney, Agent, or Firm* — Moser Taboada; Alan Taboada

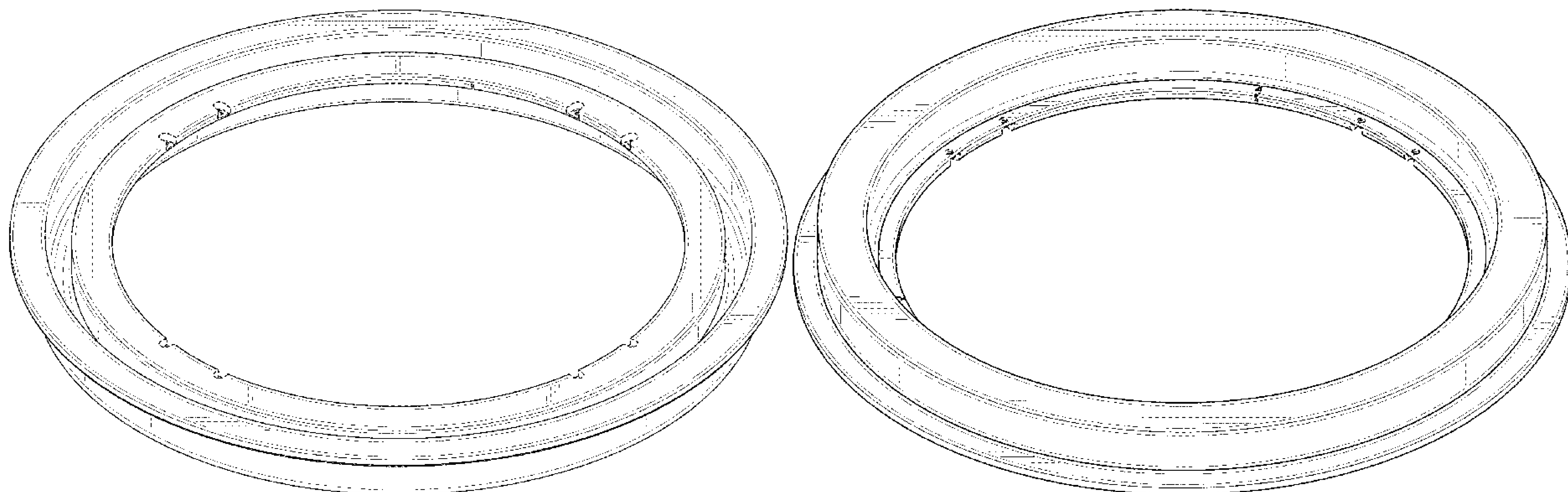
(57) **CLAIM**

The ornamental design for a process shield for a substrate processing chamber, as shown and described.

DESCRIPTION

FIG. **1** is a top isometric view of a process shield for a substrate processing chamber, showing our new design;
FIG. **2** is a bottom isometric view thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a bottom plan view thereof;
FIG. **5** is a front elevation view thereof;
FIG. **6** is a back elevation view thereof;
FIG. **7** is a left side elevation view thereof;
FIG. **8** is a right side elevation view thereof; and,
FIG. **9** is an enlarged cross sectional view taken along line **9-9** in FIG. **3**.

(Continued)



The dashed lines in FIGS. **1-9** represent unclaimed environment forming no part of the claimed design.

1 Claim, 9 Drawing Sheets

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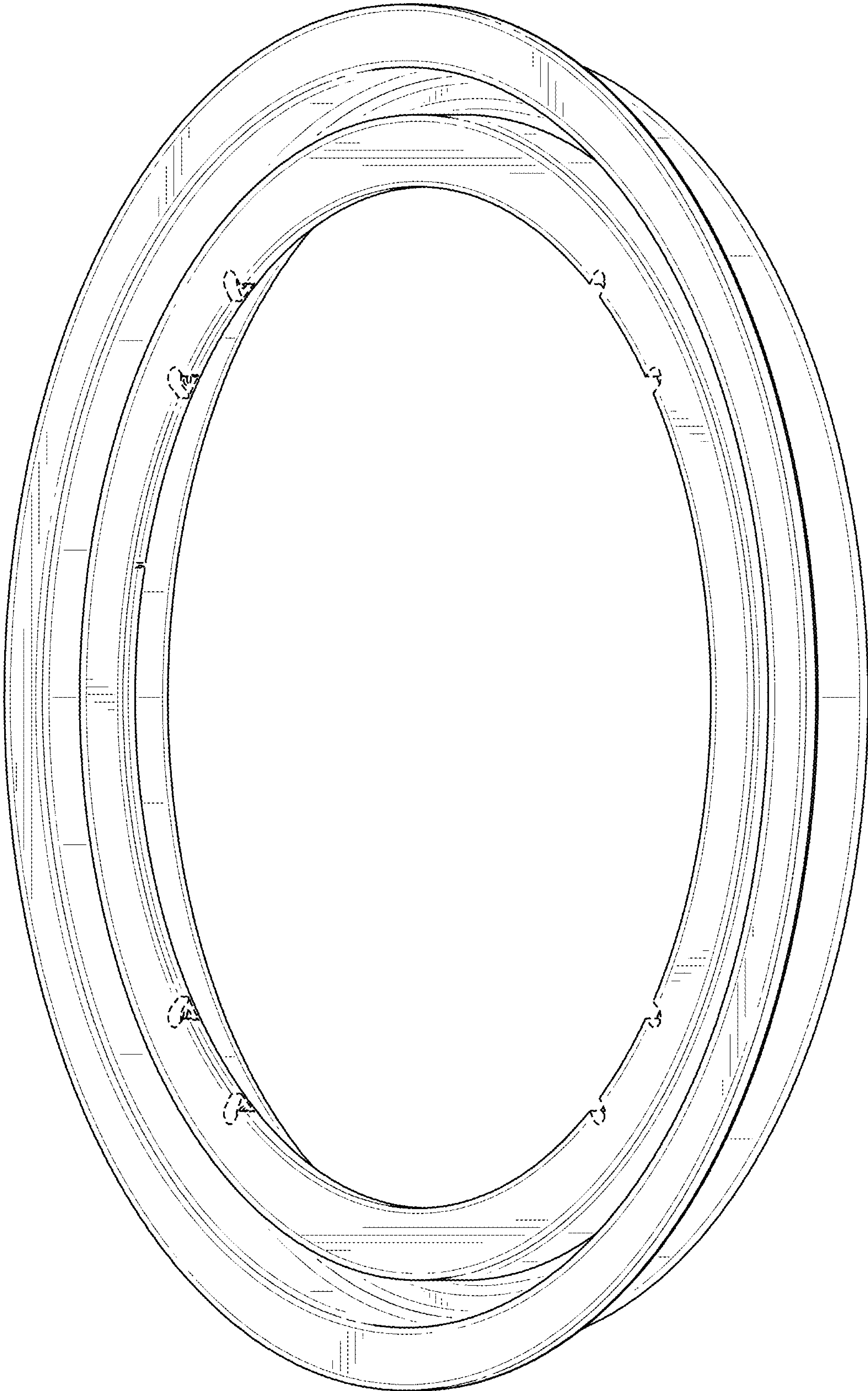

FIG. 1

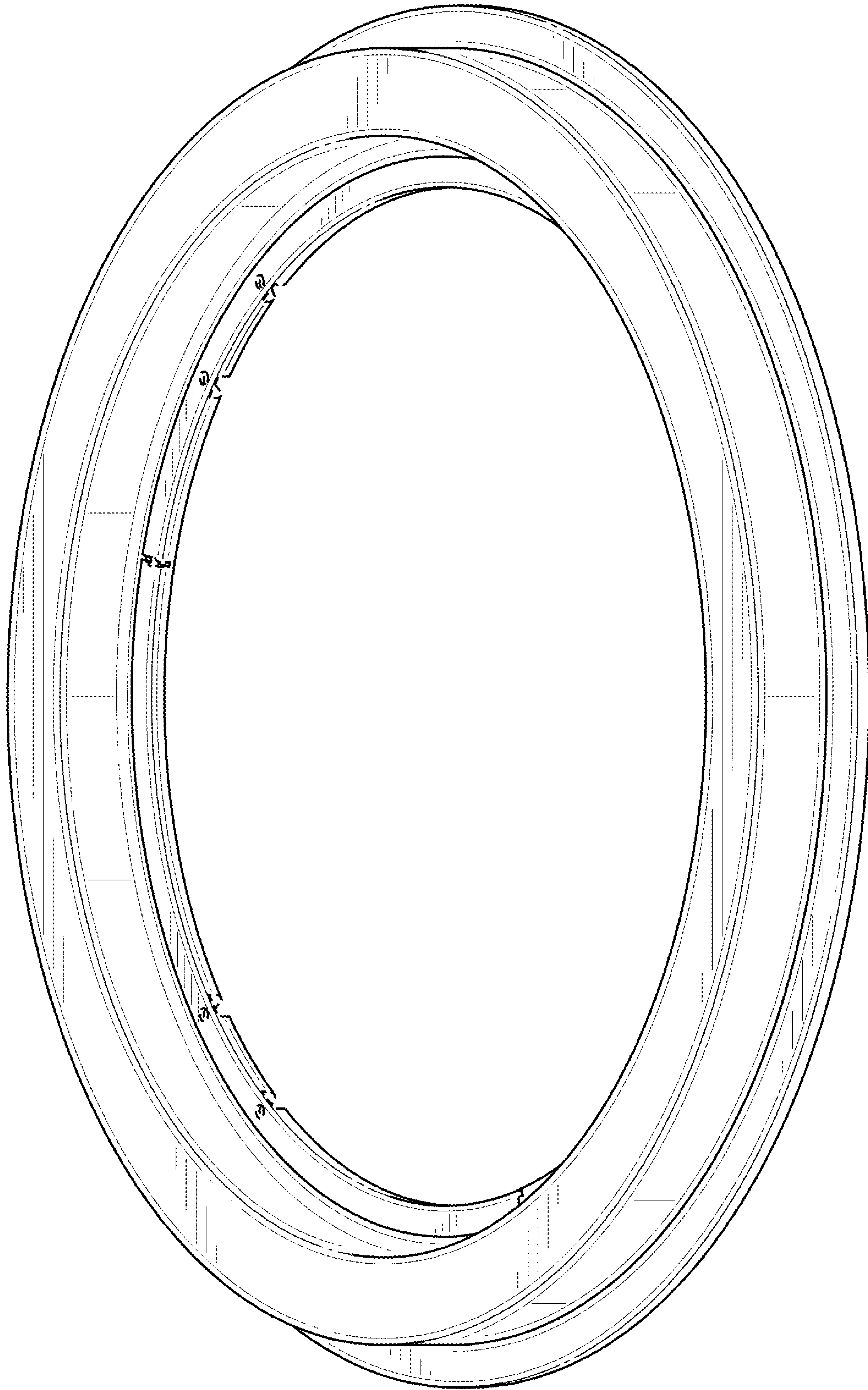

FIG. 2

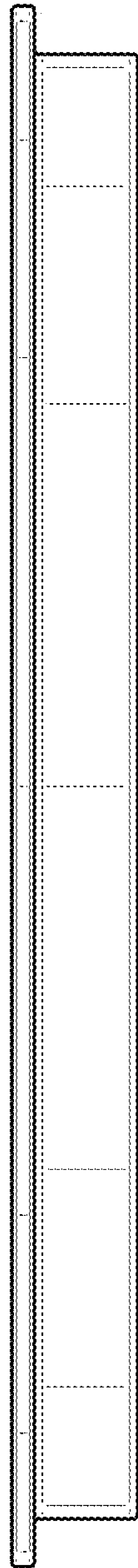

FIG. 3

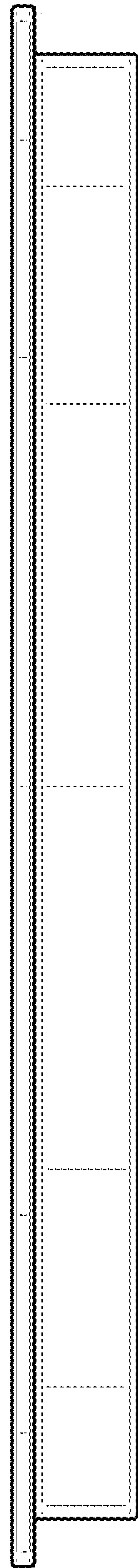

FIG. 4

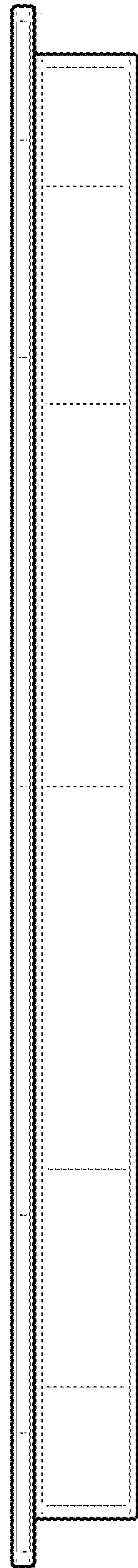

FIG. 5

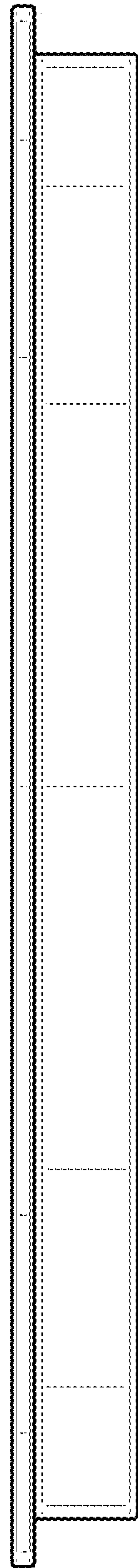

FIG. 6

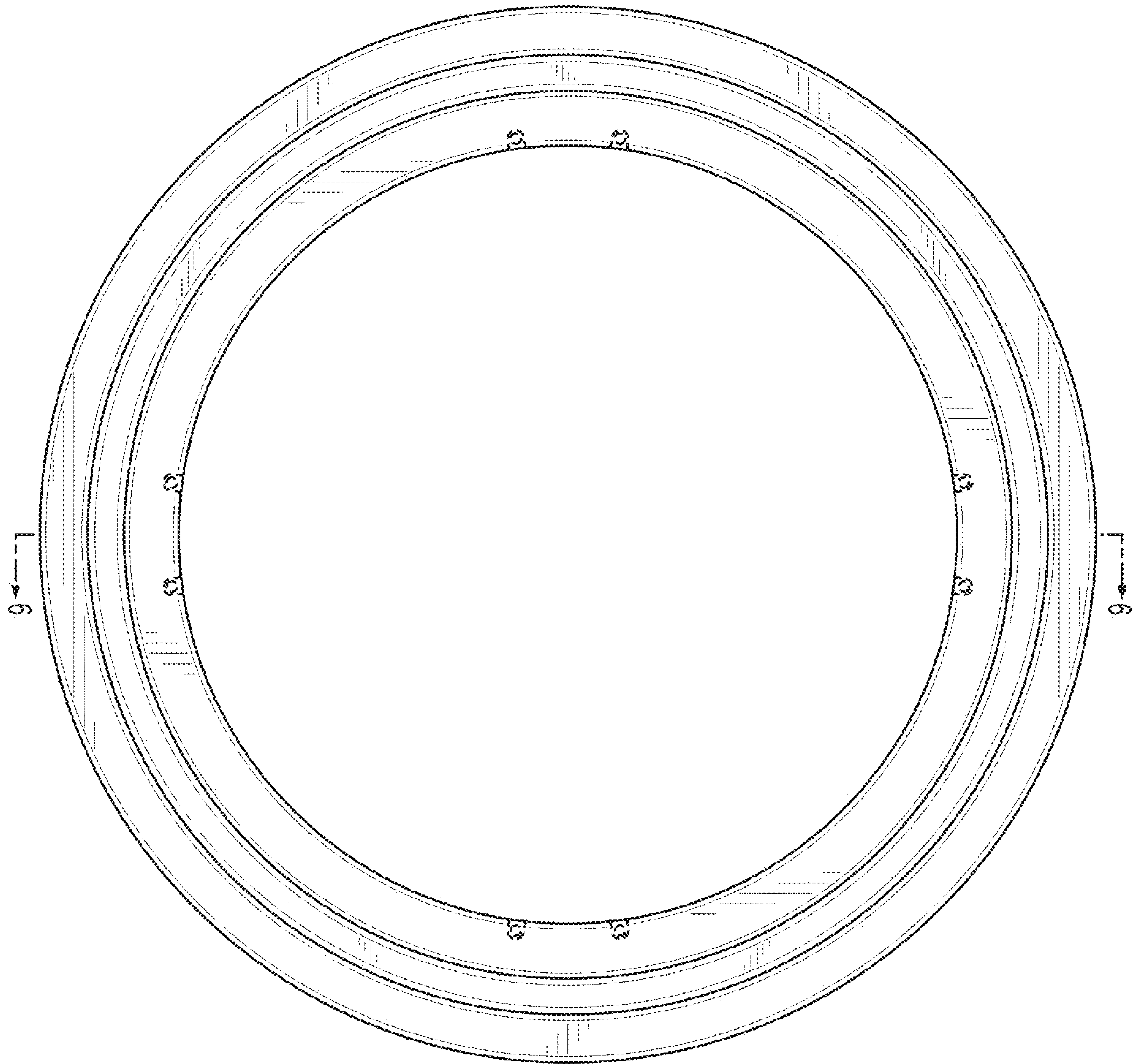

FIG. 7

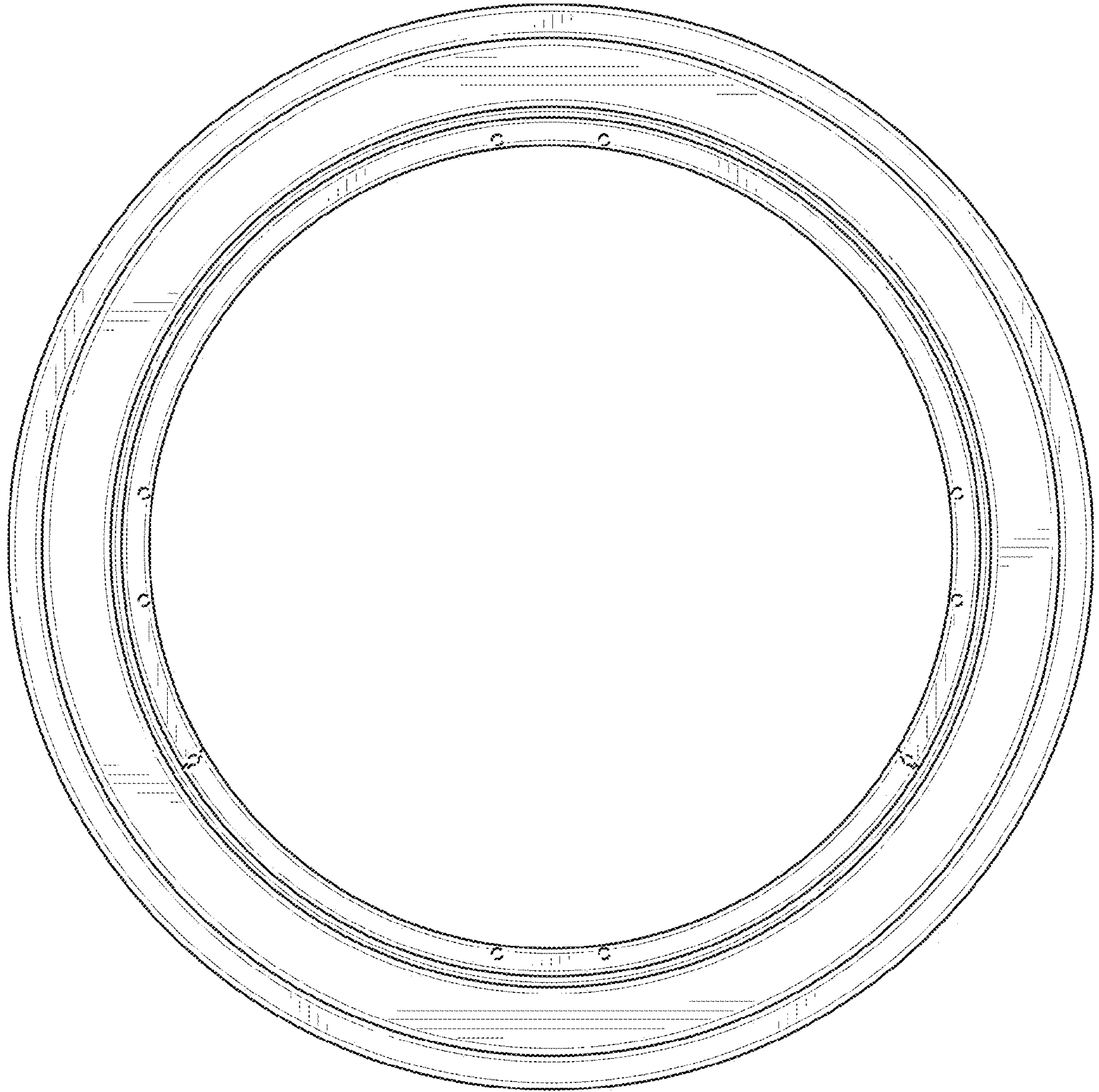

FIG. 8

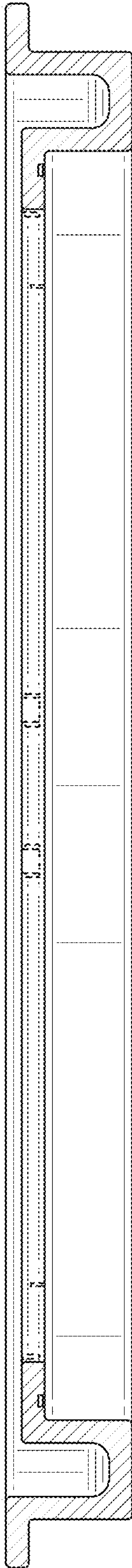

FIG. 9